Research on the mechanism of the threefold discrepancy in thermal conductivity between room temperature and phase transition temperature for 1,3,5,7tetranitro-1,3,5,7-tetrazocine (HMX) crystals

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Figure S8 Simulation of the temperature distribution of an HMX crystal containing *fast cracks* with heating time. (a) Temperature distribution of the crystals at 1 s. (b) Temperature distribution of the upper surface of the crystal at 1 s. (c) Temperature distribution of the crystal at 5 s. (d) Temperature distribution of the upper surface of the crystals at 8 s. (f) Temperature distribution of the upper surface of the crystals at 8 s. (f) Temperature distribution of the upper surface of the crystal at 5 s. (g) Temperature distribution of the crystal at 5 s. (h) Temperature distribution of the crystal at 5 s. (h) Temperature distribution of the crystal at 5 s. (g) Temperature distribution of the crystal at 18 s. (h) Temperature distribution of the upper surface of the crystal at 18 s. (h) Temperature distribution of the upper surface of the crystal at 18 s. (h) Temperature distribution of the upper surface of the crystal at 18 s. (h) Temperature distribution of the upper surface of the crystal at 18 s. (h) Temperature distribution of the upper surface of the crystal at 18 s.



Figure S9 Simulation of the temperature distribution of an HMX crystal containing *small cracks* with heating time. (a) Temperature distribution of the crystals at 1 s. (b) Temperature distribution of the upper surface of the crystal at 1 s. (c) Temperature distribution of the crystal at 5 s. (d) Temperature distribution of the upper surface of the crystal at 5 s. (e) Temperature distribution of the crystals at 8 s. (f) Temperature distribution of the upper surface of the crystal at 5 s. (g) Temperature distribution of the crystal at 5 s. (h) Temperature distribution of the crystal at 5 s. (g) Temperature distribution of the crystals at 18 s. (h) Temperature distribution of the crystal at 5 s. (g) Temperature distribution of the crystals at 18 s. (h) Temperature distribution of the crystal at 5 s. (h) Temperature distribution of the crystal at 5 s. (h) Temperature distribution of the crystal at 5 s. (h) Temperature distribution of the crystal at 5 s. (h) Temperature distribution of the crystal at 5 s. (h) Temperature distribution of the crystal at 5 s. (h) Temperature distribution of the crystal at 5 s. (h) Temperature distribution of the crystal at 5 s. (h) Temperature distribution of the crystal at 18 s. (h) Temperature distribution of the crystal at 18 s.



Figure S10 Simulation of the temperature distribution of an HMX crystal containing *fast cracks* and *small cracks* with heating time. (a) Temperature distribution of the crystals at 1 s. (b) Temperature distribution of the upper surface of the crystal at 1 s. (c) Temperature distribution of the crystal at 5 s. (d) Temperature distribution of the upper surface of the crystal at 5 s. (e) Temperature distribution of the crystals at 8 s. (f) Temperature distribution of the upper surface of the crystal at 5 s. (g) Temperature distribution of the crystal at 8 s. (h) Temperature distribution of the upper surface of the crystal at 18 s. (h) Temperature distribution of the upper surface of the crystal at 18 s.

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Parameters	HMX	Air
ρ (kg/m ³)	1960	1.204
$C_p (J/(kg \times K))$	978	1005.302
$\lambda \left(W/(m \times K) \right)$	0.518	0.026

Table S1. Values of initial thermal parameters in the models

Further detail of the simulation

As shown in Fig. S7 (a), the heating setup in the simulation is divided into the hightemperature furnace cavity, the crystal part and the crack part. The cracks and cavities fully filled with air with initial parameters shown in Table S1. The parameters of HMX were obtained from our measurements and simplified to constants in the model to focus on the effect of cracks, while the relevant parameters for air are the built-in air material parameters in COMSOL following the equation below:

$$\rho = 353.065 \times T^{-1} [kg / m^3]$$

$$C_{p} = 1047.637 - 0.373 \times T + 9.453 \times 10^{-4} \times T^{2} - 6.024 \times 10^{-7} \times T^{3} + 1.286 \times 10^{-10} \times T^{4} [J/kg \times K]$$

 $\lambda = -2.276 \times 10^{-3} + 1.155 \times 10^{-4} \times T - 7.903 \times 10^{-8} \times T^2 + 4.117 \times 10^{-11} \times T^3 - 7.439 \times 10^{-15} \times T^4 \left[W \,/ \, (m \times K) \right]$

where T is the value of the temperature in the International System of Units without the unit. The initial temperature of the model is 293.15K (T=293.15), and the bottom of the high temperature chamber is set to a constant temperature of 458.15K (T=458.15) as the only heat source. We set up the convective heat flux coefficient $h = 5 \text{ W/(m^2 \times K)}$ (normally 5-20 W/(m²×K) in air), as the heat dissipation efficiency of the high temperature cavity boundary except the bottom surface, as shown in Fig. S7 (a). The heat dissipation efficiency q satisfies the following equation:

$$q = h(T_{ext} - T)$$

where T_{ext} is the external temperature constant at 293.15K and T is the temperature at the edge of the high-temperature cavity. The finite element meshing of the model was performed using an extremely fine segmentation with a minimum cell size of about 0.5 μ m, as shown in Fig. S7 (b).